



Product Change Notification: BLAS-09IYLA056

Date:

04-Aug-2026

Product Category:

Automotive LED Drivers, General Purpose LED Drivers

Notification Subject:

CCB 8038 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MIC3203YM, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM-TR and MAQ3203YM-TRVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package assembled at MTAI site.

Affected CPNs:

[BLAS-09IYLA056_Affected_CPN_08042026.pdf](#)

[BLAS-09IYLA056_Affected_CPN_08042026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MIC3203YM, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM-TR and MAQ3203YM-TRVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package assembled at MTAI site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand	No

	(HQ) (MTAI)	(HQ) (MTAI)	
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-Free)	QMI519 (PFAS-Free)	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 02 September 2026 (date code: 2636)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	August 2026					September 2026				
Work Week	09	10	11	12	13		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date			X													
Qual Report Availability								X								
Final PCN Issue Date								X								
Estimated Implementation Date												X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 11, 2026: Issued initial notification.

August 04, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on September 02, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-09IYLA056_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MIC3203-1YM

MAQ3203YM-TRVAO

MAQ3203YM-VAO

MIC3203-1YM-TR

MIC3203YM

MIC3203YM-TR



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: BLAS-09IYLA056

Date

July 21, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MIC3203YM, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM-TR and MAQ3203YM-TRVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package assembled at MTAI site. This is an AEC-Q006 Grade 1 Qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for MIC3203-1YM, MIC3203YM, MAQ3203YM-VAO, MIC3203-1YM-TR, MIC3203YM-TR and MAQ3203YM-TRVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package assembled at MTAI site. This is an AEC-Q006 Grade 1 Qualification.

QUAL ID:	R2600234
QUAL ID Rev.:	A
MP CODE:	2A616YC2XVA1
Part No.:	MAQ3203YM-TRVAO
Bonding No.:	BD-003748A
CCB No.:	8038

Lead Frame

Paddle Size:	90x90 mils
Material:	CDA194
DAP Surface Prep:	Bare Cu
Treatment:	Roughened
Process:	Stamped
Lead Lock:	Yes
Part Number:	10100841
Lead Plating:	Matte Tin
Strip Density:	320 units/strip

Bond Wire

Wire Material:	CuPdAu wire
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Die Attach Material

Epoxy:	QMI519
Conductive:	Yes

Mold Compound

Mold Compound:	G600V
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Package

PKG Type:	SOIC
Pin/Ball Count:	8
Package Size:	150 mils

Manufacturing Information

Assembly Lot No.
MTAI264301806.000
MTAI264301819.000
MTAI264301752.000

Result: **Pass**

Conclusion:

Qualification of 2A616 mask / MAQ3203YM-TRVAO product / CuPdAu wire in 8L SOIC (150) (C2X) package at MTAI site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass	Electrical Test: Tester TMT_MCRS_NT 25°C and 125°C
High Temp Storage	175°C / 500 hours	JESD22-A103	45 units each lot / 3 lots	Electrical: 0/45, 0/45, 0/45; WBS: 0/3, 0/3, 0/3; WBP: 0/3, 0/3, 0/3	Pass	Electrical Test: Tester TMT_MCRS_NT 25°C and 125°C
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles	JESD22-A104	77 units each lot / 3 lots	Electrical: 0/77, 0/77, 0/77; WBP: 0/3, 0/3, 0/3; WBS: 0/3, 0/3, 0/3	Pass	Electrical Test: Tester TMT_MCRS_NT 25°C and 125°C
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 42.0V	JESD22-A110	77 units each lot / 3 lots	Electrical: 0/77, 0/77, 0/77; WBP: 0/3, 0/3, 0/3; WBS: 0/3, 0/3, 0/3	Pass	Electrical Test: Tester TMT_MCRS_NT 25°C and 125°C
Unbiased HAST	+130°C / 85%RH / 96 hours	JESD22-A118	77 units each lot / 3 lots	Electrical: 0/77, 0/77, 0/77	Pass	Electrical Test: Tester TMT_MCRS_NT 25°C
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass	
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5 units / 1 lot	0/5	Pass	